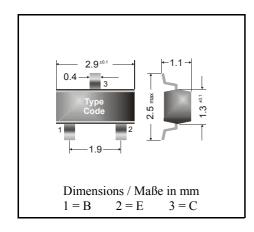


NPN Surface mount Si-Epitaxial PlanarTransistors Si-Epitaxial PlanarTransistoren für die Oberflächenmontage

NPN



Power dissipation – Verlustleistung 250 mW

Plastic case SOT-23

Kunststoffgehäuse (TO-236)

Weight approx. – Gewicht ca. 0.01 g

Plastic material has UL classification 94V-0 Gehäusematerial UL94V-0 klassifiziert

Standard packaging taped and reeled Standard Lieferform gegurtet auf Rolle

Maximum ratings $(T_A = 25^{\circ}C)$

Grenzwerte ($T_A = 25^{\circ}C$)

			BCW 60	
Collector-Emitter-voltage	B open	V_{CE0}	32 V	
Collector-Base-voltage	E open	V_{CB0}	32 V	
Emitter-Base-voltage	C open	$ m V_{EB0}$	5 V	
Power dissipation – Verlustleistung		P _{tot}	250 mW ¹)	
Collector current – Kollektorstrom (DC)		I_{C}	100 mA	
Peak Collector current – Kollektor-Spitzenstrom		I_{CM}	200 mA	
Peak Base current – Basis-Spitzenstrom		I_{BM}	200 mA	
Junction temperature – Sperrschichttemperatur		T_{j}	150°C	
Storage temperature – Lagerungstemperatur		T_{S}	- 65+ 150°C	

Characteristics $(T_j = 25^{\circ}C)$

Kennwerte $(T_j = 25^{\circ}C)$

		Min.	Typ.	Max.
Collector-Base cutoff current – Kollektorreststrom				
$I_{E} = 0, V_{CB} = 32 \text{ V}$	I_{CB0}	_	_	20 nA
$I_E = 0$, $V_{CB} = 32$ V, $T_j = 150$ °C	I_{CB0}	_	_	20 μΑ
Emitter-Base cutoff current – Emitterreststrom				
$I_{\rm C} = 0, V_{\rm EB} = 4 \text{ V}$	I_{EB0}	_	_	20 nA
Collector saturation volt. – Kollektor-Sättigungsspg. ²)				
$I_C = 10 \text{ mA}, I_B = 0.25 \text{ mA}$	V _{CEsat}	50 mV		350 mV
$I_C = 50 \text{ mA}, I_B = 1.25 \text{ mA}$	V _{CEsat}	100 mV		550 mV

01.11.2003

Mounted on P.C. board with 3 mm² copper pad at each terminal Montage auf Leiterplatte mit 3 mm² Kupferbelag (Lötpad) an jedem Anschluß

²) Tested with pulses $t_p = 300 \mu s$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300 \mu s$, Schaltverhältnis $\leq 2\%$



Characteristics $(T_i = 25^{\circ}C)$

Kennwerte $(T_i = 25^{\circ}C)$

Characteristics $(1_j = 25)$				Kennwerte	$(1_j - 23 C)$
			Min.	Тур.	Max.
Base saturation voltage – Basis-S					
$I_C = 10 \text{ mA}, I_B = 0.25 \text{ mA}$,	$V_{ ext{BE}sat}$	600 mV	_	850 mV
$I_C = 50 \text{ mA}, I_B = 1.25 \text{ mA}$		$V_{ ext{BE} ext{sat}}$	700 mV	_	1050 mV
DC current gain – Kollektor-Basis-Stromverhältnis ¹)					
	BCW 60B	\mathbf{h}_{FE}	20	_	_
$V_{CE} = 5 \text{ V}, I_{C} = 10 \mu\text{A}$	BCW 60C	h_{FE}	40	_	_
	BCW 60D	h_{FE}	100		_
	BCW 60B	$\mathbf{h}_{ ext{FE}}$	180	_	310
$V_{CE} = 5 \text{ V}, I_{C} = 2 \text{ mA}$	BCW 60C	$\mathbf{h}_{ ext{FE}}$	250	_	460
	BCW 60D	$\mathbf{h}_{ ext{FE}}$	380	_	630
	BCW 60B	h_{FE}	70	_	_
$V_{CE} = 1 \text{ V}, I_{C} = 50 \text{ mA}$	BCW 60C	h_{FE}	90	_	_
	BCW 60D	h_{FE}	100	_	_
Base-Emitter voltage – Basis-Em	itter-Spannung	1)			
$V_{CE} = 5 \text{ V}, I_{C} = 10 \mu\text{A}$		$V_{\scriptscriptstyle BEon}$	_	520 mV	_
$V_{CE} = 5 \text{ V}, I_{C} = 2 \text{ mA}$		$V_{\scriptscriptstyle BEon}$	550 mV	650 mV	700 mV
$V_{CE} = 1 \text{ V}, I_{C} = 50 \text{ mA}$		$V_{\scriptscriptstyle BEon}$	_	780 mV	_
Gain-Bandwidth Product – Transitfrequenz					
$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}, f = 100 \text{ MHz}$		f_{T}	100 MHz	250 MHz	_
Collector-Base Capacitance – Kollektor-Basis-Kapazität					
$V_{CB} = 10 \text{ V}, I_{E} = i_{e} = 0, f = 1 \text{ MHz}$		C_{CB0}	_	1.7 pF	_
Emitter-Base Capacitance – Emitter-Basis-Kapazität					
$V_{EB} = 0.5 \text{ V}, I_C = i_c = 0, f = 1 \text{ MHz}$		C_{EB0}	_	11 pF	_
Noise figure – Rauschzahl					
$V_{CE} = 5 \text{ V}, I_{C} = 200 \mu\text{A}, R_{G} = 2 k\Omega,$ $f = 1 \text{ kHz}, \Delta f = 200 \text{ Hz}$		F	_	2 dB	6 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft		R_{thA}		420 K/W ²)	
Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren		BCW 61 series			

Marking – Stempelung BCW 60B = AB BCW 60C = AC BCW 60D = AD

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Tested with pulses t_p = 300 μ s, duty cycle \leq 2% - Gemessen mit Impulsen t_p = 300 μ s, Schaltverhältnis \leq 2% Mounted on P.C. board with 3 mm² copper pad at each terminal

Mounted on P.C. board with 3 mm² copper pad at each terminal Montage auf Leiterplatte mit 3 mm² Kupferbelag (Lötpad) an jedem Anschluß